

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. - 6. (Canceled)

7. (Currently Amended) A fabrication method of a chip type power inductor comprising:

preparing green sheets [[that]] with a magnetic layer and a non-magnetic layer [[are]] respectively formed on a carrier film;

forming cutting lines on the magnetic layer green sheet and the non-magnetic layer green sheet;

forming via holes on the non-magnetic layer green sheet where the cutting lines are formed, and forming an electrode pattern at an upper surface of the non-magnetic layer green sheet;

picking up unnecessary parts from the magnetic layer green sheet and the non-magnetic layer green sheet and thus corresponding remaining parts of the magnetic substance to the picked up parts of the non-magnetic substance or corresponding the picked up parts of the magnetic substance to remaining parts of the non-magnetic substance;

stacking a plurality of layers by constituting the magnetic layer and the non-magnetic layer where via holes and electrode patterns are formed as one unit in a state that a non-magnetic layer where cutting lines and electrode patterns are not formed is inserted;

stacking a cover layer composed of a magnetic layer at upper and lower surfaces of the stacked layers;

firing the stacked body; and

forming external electrodes at an outer surface of the fired stack body.

8. (Original) The method of claim 7, wherein the magnetic layer or the non-magnetic layer on the carrier film are respectively formed by using a doctor blade tape casting method.

9. (Original) The method of claim 7, wherein the electrode pattern of an upper surface of the non-magnetic layer green sheet is formed by a screen printing.

10. (Canceled)